


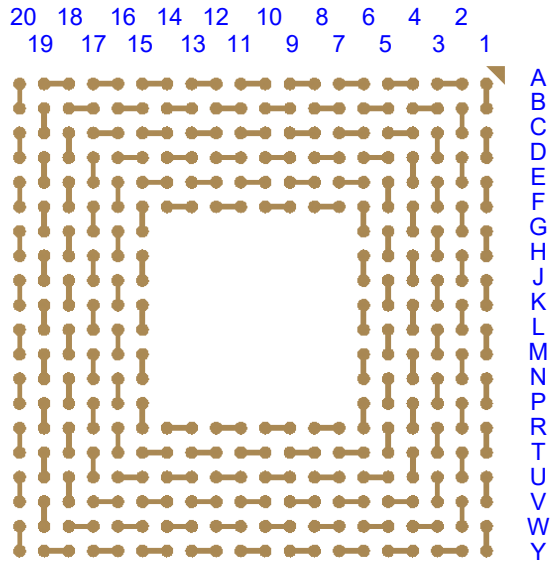
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.35mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.305mm.
- 5) PAD Cu DIAMETER: 0.457mm.
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

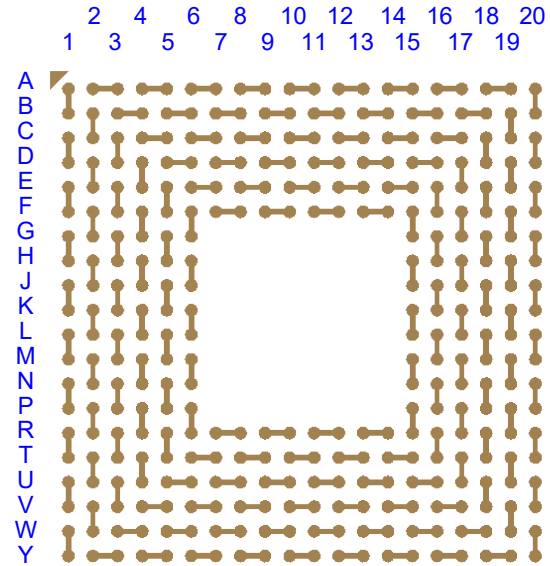
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA336T.65C-DC203D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA336T.65-DC203D	Sn63/Pb37	NO	NO	YES

APPROVALS		DATE				
DRAWN	T. Au	04/04/2022				
ENG	M. Hart	04/04/2022	TITLE		BGA336T.65C-DC203D DAISY CHAIN DUMMY	
MFG			SCALE	SIZE	DRAWING NO.	REV
QA			5:1	A	562033	A
CUST			DO NOT SCALE DRAWING		SHEET 1 OF 3	
REVISED						

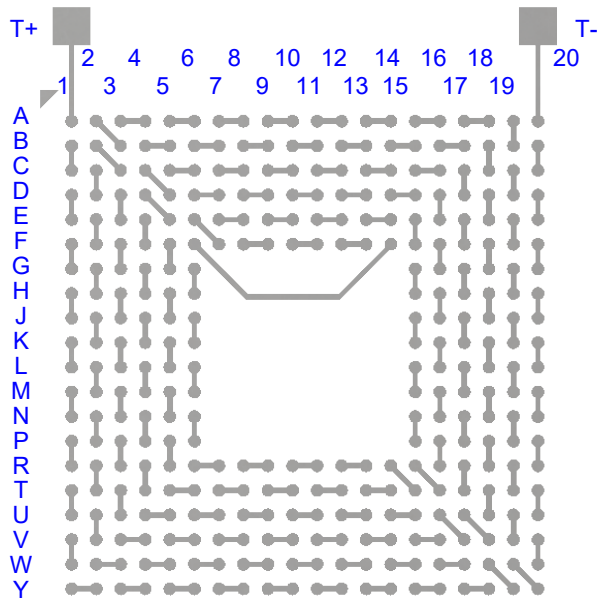
BALL VIEW



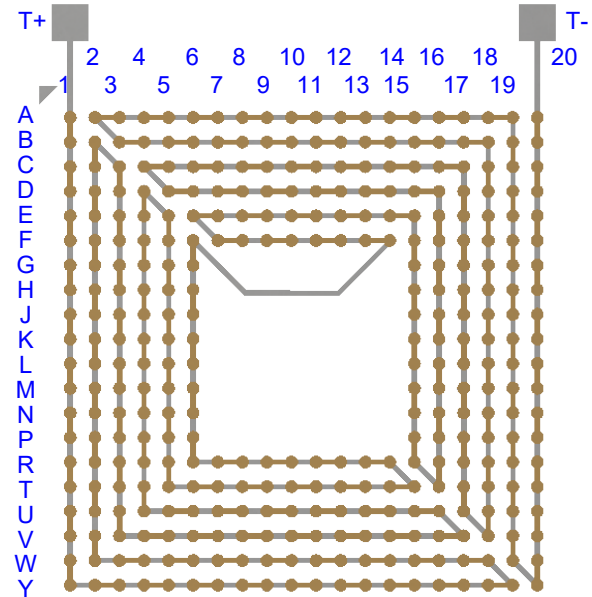
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

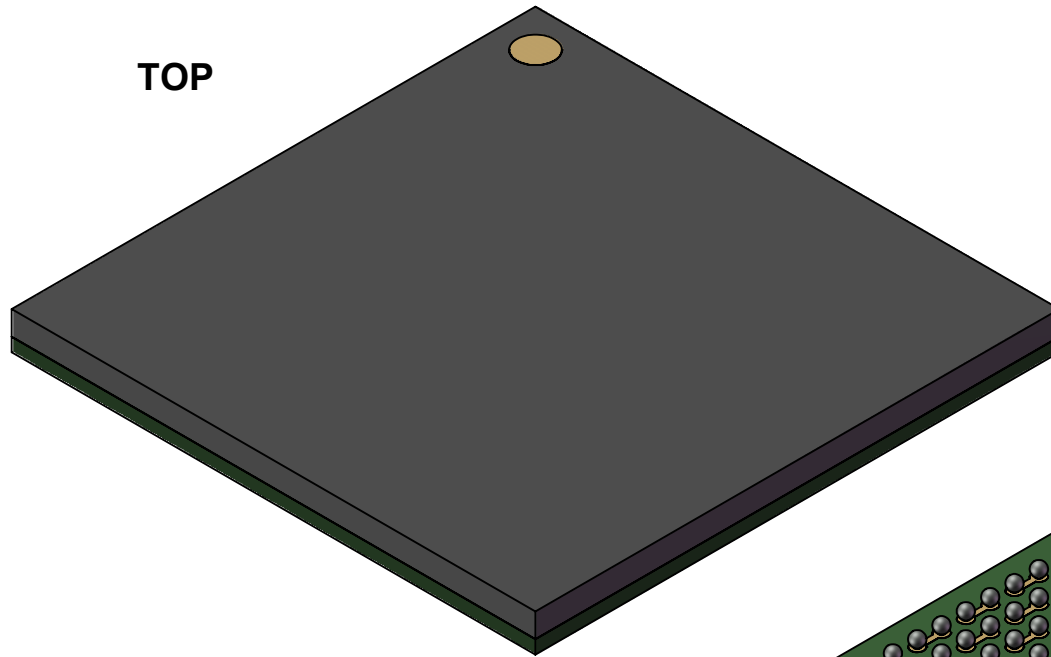
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu PAD DIAMETER 0.457mm (18mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6mil).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.305mm (12mil).

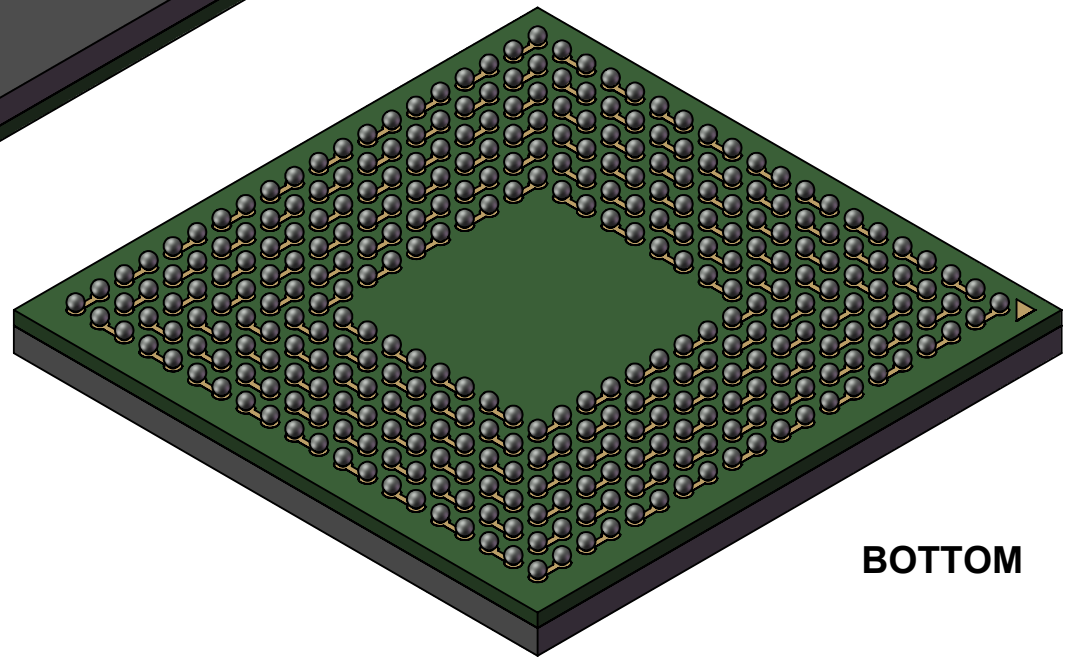
TopLine ®			
TITLE		BGA336T.65C-DC203D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
5:1	A	562033	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODEL

TOP



BOTTOM



TopLine[®]

TITLE BGA336T.65C-DC203D
DAISY CHAIN DUMMY

SCALE 7:1	SIZE A	DRAWING NO. 562033	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 3